



Bill of Materials

TI DESIGNS

Count	RefDes	Value	Description	Size	Part Number	MFR	Note
1	TP1	5013	Test Point, Orange, Thru Hole	0.125 x 0.125 inch	5013	Keystone	DNI
1	TP2	5001	Test Point, Black, Thru Hole	0.100 x 0.100 inch	5001	Keystone	DNI
1	TP3	5000	Test Point, Red, Thru Hole	0.100 x 0.100 inch	5000	Keystone	DNI
1	TP4	5002	Test Point, White, Thru Hole	0.100 x 0.100 inch	5002	Keystone	DNI
1	C1		Capacitor, Cemamic	0805			DNI
1	J3	901-144-8RFX	Connector, SMA, Straight, PC mount	0.210 sq inch	901-144-8RFX, 1408332-1	Amphenol	DNI
2	R1-2		Resistor, Chip, 1/16W, 5%	0603			DNI
1	U3	LMV321IDBVR	IC, Low Power, Single OP-Amp	SOT23-5	LMV321IDBVR	TI	
1	J5	961102-6404-AR	Header, Male 2-pin, 100mil sapcing	0.100 inch x 2	961102-6404-AR		
2	J6-7	961103-6404-AR	Header, Male 3-pin, 100mil sapcing	0.100 inch x 3	961103-6404-AR		
2	J1-2	PPTC101LFBN-RC	Header, Female 10-pin, 100mil sapcing	0.100 inch x 10	PPTC101LFBN-RC		
2	U1-2	TPL0501-10RSE	IC, 10KOhm, 256 Taps Single Chain Digital W/SPI Interface	QFN	TPL0501-10RSE	TI	

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